

IN THE CLAIMS

Claims 1-20: Previously Canceled.

21. (Previously Added) A method for producing an electronic component, comprising:
providing a substrate layer;
/ providing a solid, substantially planar optical wave-guide; and
/ laminating the solid, substantially planar optical wave-guide onto the substrate layer.
22. (Previously Added) The method of claim 21, wherein at least one of a laminating material or a cladding material is coupled to the wave-guide.
23. (Previously Added) The method of claim 22, wherein at least one of an additional layer is coupled to the laminating material or the cladding material.
24. (Previously Added) The method of claim 21, wherein providing the optical wave-guide comprises etching or molding a silicon-based material to produce the wave-guide.
25. (Presently Amended) The method of claim 21, wherein the substrate layer comprises at least two layers of materials.
26. (Previously Added) The method of claim 25, wherein the at least two materials comprises silica wafers, dielectric materials, adhesive materials, resins, metals, metal alloys, and composite materials.
27. (Previously Added) The method of claim 21, wherein the wave-guide is a silicon-based material.
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